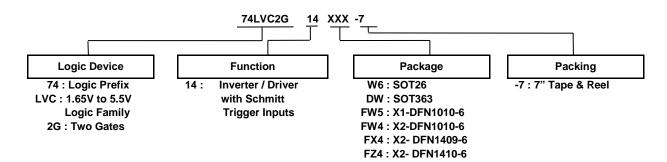


Ordering Information



Part Number	Package	Package	Package	7" Tape and F	Reel (Note 5)
Part Number	Code	(Note 4)	Size	Quantity	Part Number Suffix
74LVC2G14W6-7	W6	SOT26	2.8mm × 2.2mm × 1.1mm 0.95mm lead pitch	3000/Tape & Reel	-7
74LVC2G14DW-7	DW	SOT363	SOT363 2.0mm × 2.0mm × 1.1mm 0.65mm lead pitch		-7
74LVC2G14FW5-7	FW5	X1-DFN1010-6	1.0mm × 1.0mm × 0.5mm 0.35mm pad pitch	5000/Tape & Reel	-7
74LVC2G14FW4-7	FW4 X2-DFN1010-6		1.0mm × 1.0mm × 0.4mm 0.35mm pad pitch	5000/Tape & Reel	-7
74LVC2G14FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm × 0.9mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7
74LVC2G14FZ4-7	FZ4	X2-DFN1410-6	1.4mm × 1.0mm × 0.4mm 0.5mm pad pitch	5000/Tape & Reel	-7

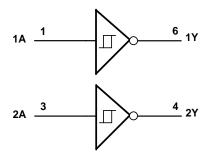
Notes:

- 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 5. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

Pin Descriptions

Pin Name	Pin Number	Function	
1A	1	Data Input	
GND	2	Ground	
2A	3	Data Input	
2Y	4	Data Output	
V _{CC}	5	Supply Voltage	
1Y	6	Data Output	

Logic Diagram



Function Table

Inputs	Output
Α	Y
Н	L
L	Н



Absolute Maximum Ratings (Notes 6 and 7) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +6.5	V
Vı	Input Voltage Range	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High or Low State	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
lok	Output Clamp Current V _O < 0	-50	mA
Io	Continuous Output Current	-50	mA
_	Continuous Current Through V _{DD} or GND	±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Note:

Recommended Operating Conditions (Note 8) (@T_A = +25°C, unless otherwise specified.)

Symbol		Parameter	Min	Max	Unit	
	On arating Valtage	Operating	1.65	5.5	V	
V _{CC}	Operating Voltage	Data Retention Only	1.5	_	V	
VI	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	V _{CC}	V	
		V _{CC} = 1.65V	_	-4		
		$V_{CC} = 2.3V$	_	-8		
I _{OH}	High-Level Output Current	V 2V	_	-16	mA	
		Vcc = 3V	_	-24		
		V _{CC} = 4.5V	_	-32		
		V _{CC} = 1.65V	_	4		
		V _{CC} = 2.3V	_	8		
I _{OL}	Low-Level Output Current	V 2V	_	16	mA	
		Vcc = 3V	_	24		
		$V_{CC} = 4.5V$	_	32		
		$V_{CC} = 1.8V \pm 0.15V, 2.5V \pm 0.2V$	_	20		
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 3.3V \pm 0.3V$	_	10	ns/V	
		$V_{CC} = 5V \pm 0.5V$	_	5		
T _A	Operating Free-air Temperature	_	-40	+125	°C	

Note: 8. Unused inputs should be held at V_{CC} or Ground.

^{6.} Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

^{7.} Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

		T 10 1111	.,	-40°C to	+85°C	-40°C to	+125°C	
Symbol	Parameter	Test Conditions	V _{cc}	Min	Max	Min	Max	Unit
			1.8V	0.70	1.50	0.70	1.70	
			2.3V	1.00	1.80	1.00	2.00	
V _{T+}	Positive-going Input Threshold Voltage	_	3V	1.30	2.20	1.30	2.40	V
	Tonago		4.5V	1.90	3.10	1.90	3.30	
			5.5V	2.20	3.60	2.20	3.80	
			1.8V	0.25	0.90	0.25	1.10	
			2.3V	0.40	1.15	0.4	1.35	
V _{T-}	Negative-Going Input Threshold Voltage	_	3V	0.60	1.50	0.6	1.7	V
		4.5V	1.00	2.00	1	2.2		
			5.5V	1.20	2.30	1.2	2.5	
			1.8V	0.15	1.00	0.15	1.20	
		_	2.3V	0.25	1.10	0.25	1.30	V
ΔV_{T}	Hysteresis (V _{T+} -V _{T-)}		3V	0.40	1.20	0.40	1.40	
	(VI+ -VI-)		4.5V	0.60	1.50	0.60	1.70	
			5.5V	0.70	1.70	0.70	1.90	
		I _{OH} = -100μA	1.65V to 5.5V	V _{CC} – 0.1		V _{CC} - 0.1		
		I _{OH} = -4mA	1.65V	1.2	_	0.95	_	
.,		I _{OH} = -8mA	2.3V	1.9	_	1.7	_	.,
Voн	High-Level Output Voltage	I _{OH} = -16mA	0)/	2.4	_	1.9	_	V
		I _{OH} = -24mA	3V	2.3	_	2.0	_	
		I _{OH} = -32mA	4.5V	3.8	_	3.4	_	
		I _{OL} = 100μA	1.65V to 5.5V	_	0.1	_	0.10	
		I _{OL} = 4mA	1.65V	_	0.45	_	0.70	
.,	Lave Lavel Outset Walter	I _{OL} = 8mA	2.3V	_	0.3	_	0.45	.,
V _{OL} Low-Level	Low-Level Output Voltage	I _{OL} = 16mA	0) /	_	0.4	_	0.60	V
		I _{OL} = 24mA	3V	_	0.55	_	0.80	
		I _{OL} = 32mA	4.5V	_	0.55	_	0.80	
I ₁	Input Current	V _I = 5.5V or GND	0 to 5.5V	_	± 5	_	±20	μA
loff	Power Down Leakage Current	V_{I} or $V_{O} = 5.5V$	0	_	± 10	_	±20	μA
Icc	Supply Current	$V_I = 5.5V$ or GND, $I_O = 0$	1.65V to 5.5V	_	10	_	40	μΑ



$\label{eq:package Characteristics (@T_A = +25 °C, V_{CC} = 3.3 V, unless otherwise specified.)}$

Symbol	Parameter	Package	Conditions	Min	Тур	Max	Unit
Cı	Input Capacitance	Typical of all packages	$V_{CC} = 3.3V$ $V_I = V_{CC}$ or GND	_	3.5	_	pF
		SOT26		_	204	_	
		SOT363		_	371	_	
	Thermal Resistance	X2-DFN1410-6	(NI-1-0)	_	430	_	0000
Θ _{JA} Junction-to-Ambient	X2-DFN1409-6	(Note 9)	_	450	_	°C/W	
		X1-DFN1010-6		_	495	_	
		X2-DFN1010-6		_	510	_	
		SOT26		_	52	_	
		SOT363		_	143	_	
	Thermal Resistance	X2-DFN1410-6	(1)	_	190	_	°C/W
θ _{JC}	Junction-to-Case	X2-DFN1409-6	(Note 9)	_	225	_	
		X1-DFN1010-6		_	245	_	
		X2-DFN1010-6		_	250	_	

Note:

Switching Characteristics

 $T_A = -40$ °C to +85°C, $C_L = 30$ or 50pF (see Figure 1)

Parameter	From (Input)	TO (OUTPUT)		= 1.8V .15V		= 2.5V).2V	V _{CC} = ± 0	: 3.3V :3V	V _{CC} ± 0	= 5V).5V	Unit
	(mpat)	(0011 01)	Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD}	Α	Υ	0.5	11.0	0.5	6.5	0.5	6.0	0.5	4.3	ns

 $T_A = -40$ °C to +125°C, $C_L = 30$ or 50pF (see Figure 1)

Parameter	Parameter From TO (Input) (OUTPUT)	V _{CC} = 1.8V ± 0.15V			: 2.5V).2V	V _{CC} = 3.3V ± 0.3V		V _{CC} = 5V ± 0.5V		Unit	
	(iliput)	(0011 01)	Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD}	Α	Y	0.5	12.0	0.5	7.2	0.5	6.7	0.5	4.7	ns

Operating Characteristics

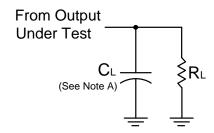
 $T_A = +25$ °C

	Parameter	Test Conditions	V _{CC} = 1.8V	V _{CC} = 2.5V	V _{CC} = 3.3V Typ	V _{CC} = 5V Typ	Unit
C _{PD}	Power Dissipation Capacitance	f = 10MHz	17	19	20	21	pF

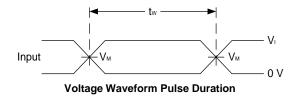
^{9.} Test condition for all packages: Device mounted on FR-4 substrate PC board, 2oz copper with minimum recommended pad layout.

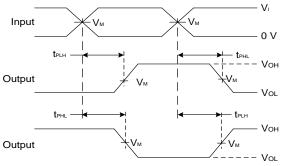


Parameter Measurement Information



V	Inp	outs	V	_	9	
V _{CC}	VI	t _R /t _F	V _M	C∟	RL	
1.8V±0.15V	Vcc	≤2ns	V _{CC} /2	30pF	1kΩ	
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω	
3.3V±0.3V	3V	≤2.5ns	1.5V	5pF	500Ω	
5V±0.5V	Vcc	≤2.5ns	V _{CC} /2	50 pF	500Ω	





Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Figure 1 Load Circuit and Voltage Waveforms

Notes:

A. Includes test lead and test apparatus capacitance. B. All pulses are supplied at pulse repetition rate \leq 10MHz.

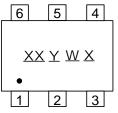
C. Inputs are measured separately one transition per measurement.

D. t_{PLH} and t_{PHL} are the same as t_{PD} .



Marking Information

(1) SOT26, SOT363



XX: Identification code

Y: Year 0~9

 \underline{W} : Week: A~Z: 1~26 week;

a~z: 27~52 week; z represents 52 and 53 week

X: A~Z: Internal Code

Part Number	Package	Identification Code
74LVC2G14W6-7	SOT26	Z5
74LVC2G14DW-7	SOT363	Z 5

(2) X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, X2-DFN1410-6

(Top View)



XX: Identification Code

<u>Y</u> : Year : 0~9

\overline{\mathbb{W}}: Week: A~Z: 1~26 week; a~z: 27~52 week; z represents

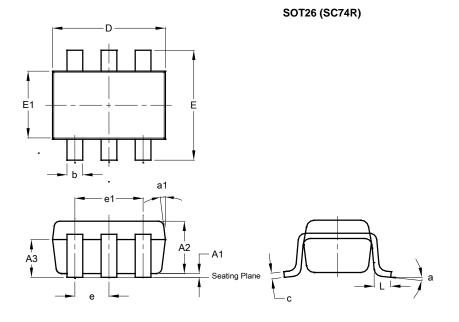
52 and 53 week \underline{X} : A~Z: Internal code

Part Number	Package	Identification Code
74LVC2G14FW4-7	X2-DFN1010-6	Z5
74LVC2G14FW5-7	X1-DFN1010-6	W5
74LVC2G14FX4-7	X2-DFN1409-6	X5
74LVC2G14FZ4-7	X2-DFN1410-6	Z5

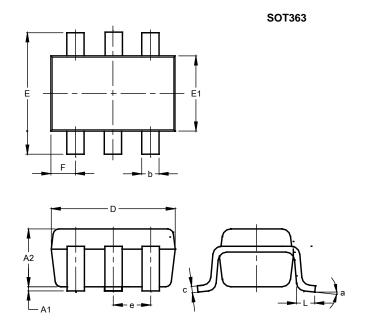


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT26 (SC74R)			
Dim				
			Тур	
A1	0.013	0.10	0.05	
A2	1.00	1.30	1.10	
А3	0.70	0.80	0.75	
b	0.35	0.50	0.38	
С	0.10	0.20	0.15	
D	2.90	3.10	3.00	
е	-	-	0.95	
e1	-	-	1.90	
Е	2.70	3.00	2.80	
E1	1.50	1.70	1.60	
L	0.35	0.55	0.40	
а	-	-	8°	
a1	-	-	7°	
All Dimensions in mm				



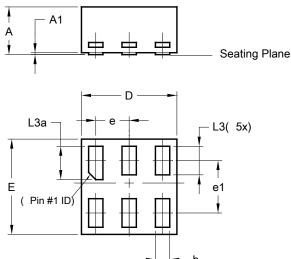
	SO	T363	_
Dim	Min	Max	Тур
A 1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
С	0.10	0.22	0.11
D	1.80	2.20	2.15
Е	2.00	2.20	2.10
E1	1.15	1.35	1.30
е	e 0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
а	0°	8°	
All Dimensions in mm			



Package Outline Dimensions (continued)

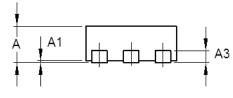
Please see http://www.diodes.com/package-outlines.html for the latest version.

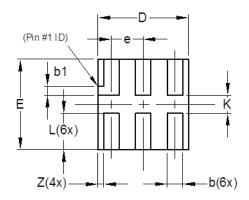
X1-DFN1010-6 (Type B)



	X1-DFN1010-6			
	(Ty	pe B)		
Dim	Min	Max	Тур	
Α		0.50	0.39	
A1		0.04	_	
b	0.12	0.20	0.15	
D	0.95	1.050	1.00	
Е	0.95	1.050	1.00	
е	0.35 BSC			
e1	0.55 BSC			
L3	0.27	0.30	0.30	
L3a	0.32	0.40	0.35	
All	All Dimensions in mm			

X2-DFN1010-6





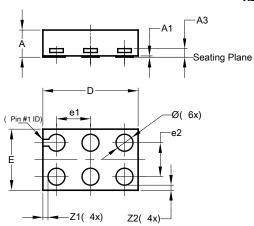
X2-DFN1010-6			
Dim	Min	Max	Тур
Α		0.40	0.39
A1	0.00	0.05	0.02
A3		_	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
е	_	_	0.35
L	0.35	0.45	0.40
K	0.15	_	_
Z	_	_	0.065
All Dimensions in mm			



Package Outline Dimensions (continued)

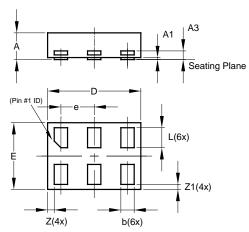
Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1409-6



	X2-DFN1409-6			
Dim	Min	Max	Тур	
Α	_	0.40	0.39	
A1	0	0.05	0.02	
A3	_	_	0.13	
Ø	0.20	0.30	0.25	
D	1.35	1.45	1.40	
Е	0.85	0.95	0.90	
e1	_		0.50	
e2			0.50	
Z1			0.075	
Z2			0.075	
All Dimensions in mm				

X2-DFN1410-6



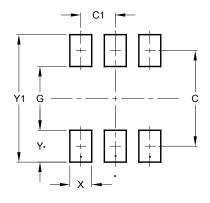
X2-DFN1410-6			
Dim	Min	Max	Тур
Α	_	0.40	0.39
A1	0.00	0.05	0.02
A3	_	_	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
Е	0.95	1.05	1.00
е			0.50
L	0.25	0.35	0.30
Z			0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			



Suggested Pad Layout

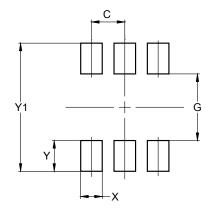
Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT26 (SC74R)



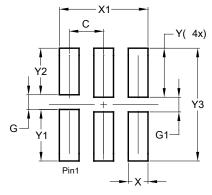
Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20

SOT363



Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.420
Y	0.600
Y1	2.500

X1-DFN1010-6 (Type B)



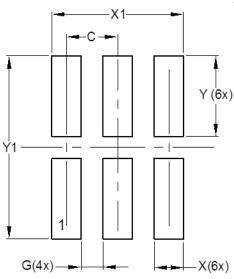
Dimensions	Value (in mm)
С	0.350
G	0.150
G1	0.150
Х	0.200
X1	0.900
Υ	0.500
Y1	0.525
Y2	0.475
Y3	1.150



Suggested Pad Layout (continued)

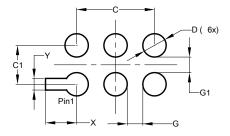
Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1010-6



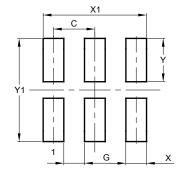
Dimensions	Value (in mm)
С	0.350
G	0.150
Х	0.200
X1	0.900
Y	0.550
Y1	1.250

X2-DFN1409-6



Dimensions	Value (in mm)
С	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
Х	0.400
Υ	0.150

X2-DFN1410-6



Dimensions	Value (in mm)
С	0.500
G	0.250
Х	0.250
X1	1.250
Y	0.525
V1	1 250



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